



# 7<sup>th</sup> IEEE Electron Devices Technology and Manufacturing (EDTM) Conference 2023

March 7 – 10, 2023 / COEX Seoul, Korea

22A. Advanced Packaging Structure and Process	
Session Date:	March 8(Wed.), 2023
Session Time:	17:00-18:40
Session Room:	Room A (#301)
Session Chair:	Prof. Caroline Sunyoung Lee (Hanyang university)
	Dr. Yik Yee Tan (Yole Intelligence)

[22A-1] [Invited]

17:00-17:25

## Latest Interconnection Technologies and Package Substrate Trend

Eun-Yong Chung, Seong-Bo Shim and Sung-Gil Kim

*Intel Corp.*

[22A-2] [Invited]

17:25-17:50

## Advanced SiC Power Technology and Package

ByongJin Kim<sup>1</sup>, Alexander Bolotnikov<sup>2</sup>, Helen Jeong<sup>1</sup>, Chandong Kim<sup>1</sup>, Hrishkesh Das<sup>2</sup> and Ganesh Ponram<sup>2</sup>

<sup>1</sup>onsemi Korea, <sup>2</sup>onsemi USA

[22A-3] [Invited]

17:50-18:15

## Strategies for Mechanically Reliable Thin-Film Flexible Electronics

Taek-Soo Kim

*Korea Advanced Institute of Science and Technology*

[22A-4] [Invited]

18:15-18:40

## Thermoreflectance-Based Thermometry for Electronics Packaging

Hyejin Jang

*Seoul National University*